

ABSTRACT OF THE DISCLOSURE

A wiring board houses a bare radio-frequency IC. Shield wiring films are provided above and below the IC. A plurality of shield interlayer-connection conductor films, i.e., shield via-holes, is provided so as to surround the IC. The shield wiring films and the shield interlayer-connection conductor films define a shield cage, which can electrostatically shield the IC. Thus, there is no need to attach a shield cap.